

## PATENT ASSIGNMENT COVER SHEET

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|---|----------------------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                   |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                       |
| <b>CONVEYING PARTY DATA</b>   |                                  |
| <b>Name</b>   | <b>Execution Date</b>            |
| WEI CUI   | 04/10/2019                       |
| KUN WANG  | 04/03/2019                       |
| JUNPING ZHAO  | 03/28/2019                       |
| <b>RECEIVING PARTY DATA</b>   |                                  |
| <b>Name:</b>  | EMC IP HOLDING COMPANY LLC       |
| <b>Street Address:</b>  | 176 SOUTH STREET                 |
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| <b>State/Country:</b>   | MASSACHUSETTS                    |
| <b>Postal Code:</b>   | 01748                            |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                  |
| <b>Property Type</b>  | <b>Number</b>                    |
| <b>Application Number:</b>  | 16381849                         |
| <b>CORRESPONDENCE DATA</b>  |                                  |
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| <b>ATTORNEY DOCKET NUMBER:</b>  | 110534.02                        |
| <b>NAME OF SUBMITTER:</b>   | WILLIAM E. LEWIS                 |
| <b>SIGNATURE:</b>   | /William E. Lewis/               |
| <b>DATE SIGNED:</b>   | 04/11/2019                       |
| <b>Total Attachments: 5</b>   |                                  |
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## ASSIGNMENT

**WHEREAS**, we, Wei Cui, Kun Wang and Junping Zhao, have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled **METHOD, DEVICE AND COMPUTER PROGRAM PRODUCT FOR MANAGING DISTRIBUTED SYSTEM**, the specification of which:

☒ [X] is being executed on even date herewith and is about to be filed in the United States Patent Office;

☐ [ ] was filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_;

☐ [ ] was patented under U.S. Patent No. \_\_\_\_\_ on \_\_\_\_\_.

**WHEREAS**, EMC IP Holding Company LLC (hereinafter "ASSIGNEE"), a limited liability company organized and existing under the laws of the State of Delaware and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

**NOW, THEREFORE**, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

**AND**, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution,

reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

**AND**, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives.

**IN TESTIMONY WHEREOF**, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2019.4.10

Wei Cui

Inventor's Signature

Print full name of first inventor:

Wei Cui

Residence:

Beijing, China

Citizenship:

China

Mailing Address:

8F, Building D, Tsinghua Science Park  
No. 1 Chengfu Road  
Beijing, China 100084

I Zhu Yi Jiam (name) whose residential address is  
EECS, PKU

was personally present and did see Wei Cui (name of person signing the assignment) who is personally known to me, execute the above assignment.

Zhu Yi Jiam (signature of first witness)

Signed at EECS, PKU (location of witness signature)

on this day 4.11 of 2019. (date of signature)

I Zhong Yehong (name) whose residential address is  
EECS, PKU

was personally present and did see Wei Cui (name of person signing the assignment) who is personally known to me, execute the above assignment.

Zhong Yehong (signature of second witness)

Signed at EECS, PKU (location of witness signature)

on this day 4.11 of 2019. (date of signature)

Date: April 3, 2019



\_\_\_\_\_  
Inventor's Signature

Print full name of second inventor: Kun Wang  
Residence: Beijing, China  
Citizenship: China  
Mailing Address: No. 288, Chaoyangmennei Dajie  
Dongcheng District  
Beijing, China 100010

I \_\_\_\_\_ (name) whose residential address is

\_\_\_\_\_  
was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

\_\_\_\_\_  
(signature of first witness)

Signed at \_\_\_\_\_ (location of witness signature)

on this day \_\_\_\_\_ of 20\_\_\_\_. (date of signature)

I \_\_\_\_\_ (name) whose residential address is

\_\_\_\_\_  
was personally present and did see Kun Wang (name of person signing the assignment) who is personally known to me, execute the above assignment.

\_\_\_\_\_  
(signature of second witness)

Signed at \_\_\_\_\_ (location of witness signature)

on this day \_\_\_\_\_ of 20\_\_\_\_. (date of signature)

Date: March 28

Junping Zhao  
Inventor's Signature

Print full name of third inventor: Junping Zhao  
Residence: Beijing, China  
Citizenship: China  
Mailing Address: 18<sup>th</sup> Floor  
Block D, Tsinghua Science Park No. 1  
Zhong Guan Cun East Road  
Beijing, China 100084

I SANPING LI (name) whose residential address is  
Beijing 100084, China

was personally present and did see Junping Zhao (name of person signing the assignment) who is personally known to me, execute the above assignment.

[Signature] (signature of first witness)

Signed at Tsinghua Sci & Tech Building D, Beijing (location of witness signature)

on this day March 28 of 2019. (date of signature)

I Chenxi Hu (name) whose residential address is  
Tsinghua Sci & Tech Beijing D, Beijing

was personally present and did see Junping Zhao (name of person signing the assignment) who is personally known to me, execute the above assignment.

Chenxi Hu (signature of second witness)

Signed at Tsinghua Sci & Tech Beijing D, Beijing (location of witness signature)

on this day March 28 of 2019. (date of signature)